

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Semiconductor devices – Mechanical and climatic test methods –
Part 26: Electrostatic discharge (ESD) sensitivity testing – Human body model
(HBM)**

**Dispositifs à semiconducteurs – Méthodes d'essais mécaniques et climatiques –
Partie 26: Essai de sensibilité aux décharges électrostatiques (DES) – Modèle du
corps humain (HBM)**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –****Part 26: Electrostatic discharge (ESD) sensitivity testing –
Human body model (HBM)**

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This edition includes the following significant technical changes with respect to the previous edition:

- a) a new subclause relating to HBM stressing with a low parasitic simulator is added, together with a test to determine if an HBM simulator is a low parasitic simulator;

- b) a new subclause is added for cloned non-supply pins and a new annex is added for testing cloned non-supply pins.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47/2438/FDIS	47/2454/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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